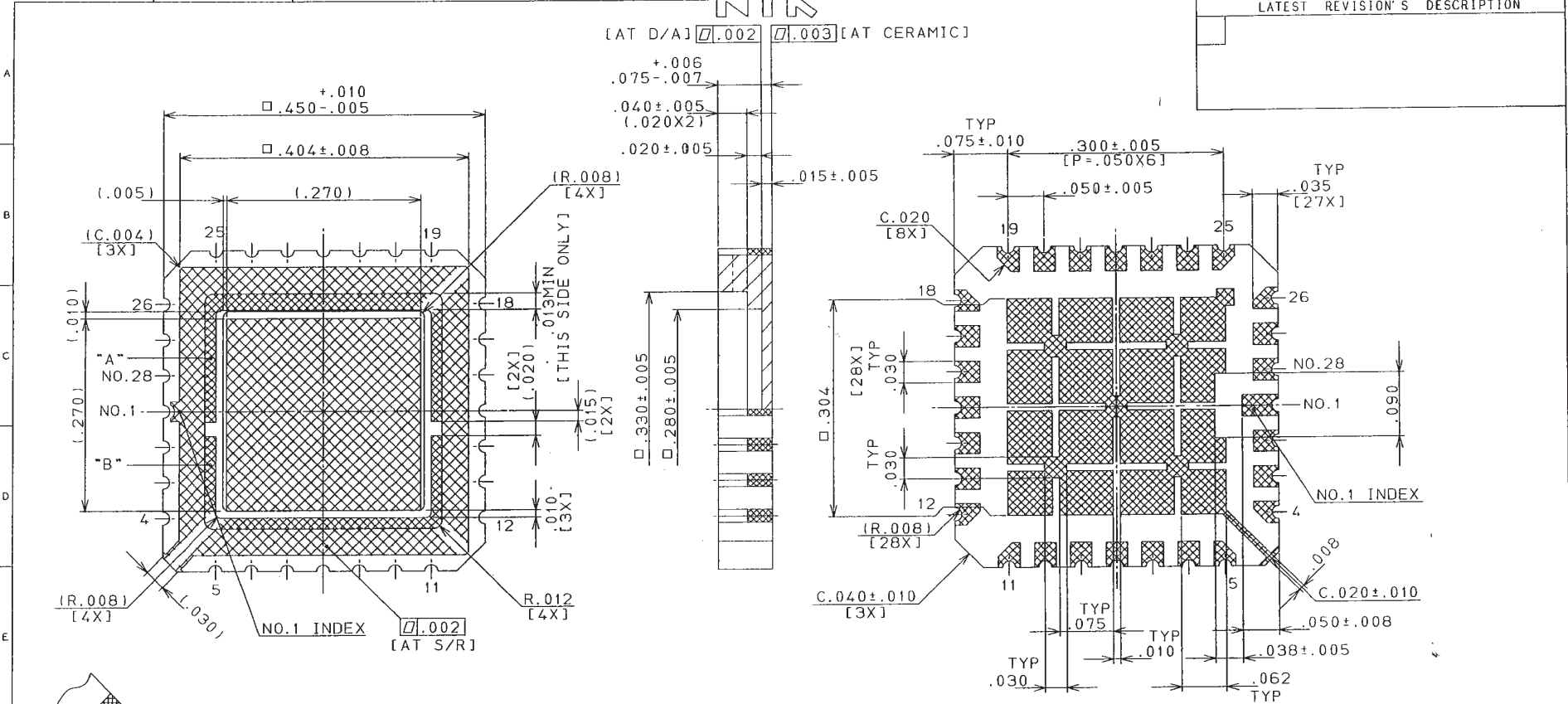


NTK TECHNICAL CERAMICS

LATEST REVISION'S DESCRIPTION	



- NOTES: 1. GOLD PLATE 60μ INCHES MIN OVER 80μ INCHES MIN NICKEL.
 2. SEAL RING TO BE ISOLATED FROM ANY LEADS.
 3. NO.4~12 LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD.
 4. NO.1 & 15~28 LEAD TO BE CONNECTED TO B/G PAD "A".
 NO.2,3,13 & 14 LEAD TO BE CONNECTED TO B/G PAD "B".
 5. SEAL RING & DIE ATTACH PAD TO BE METALLIZED.

発行
98.7.31
技術部
部品管理課

MODIFIED DWG NO. IRK28F1-5636F

3					
2					
1	CERAMIC	BLACK ALUMINA		NEW DRAWING	JUL -15 -1998
Item	Name	Material	Description	Rev.	Date
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1%					
DRAWN T. SHIGURO					
N. L. T. 2 DECIMALS - XX ± .01					
3 DECIMALS - XXX ± .005					
CHECKED I. MIWA					
TITLE NTK TECHNICAL CERAMICS					
CUSTOMER CHELSEA TECHNOLOGY					
APPROVED H. NAKAMURA					
UNIT INCH					
SCALE /					
DWG NO. PB-C88585-A				28 LEAD CHIP CARRIER	
				DWG NO. IRK28F1-5636G	
				SIZE A-C	